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74LCX07

Low Voltage Hex Buffer with Open Drain Outputs

Features

- 5V tolerant inputs
- 2.3V to 5.5V V_{CC} specifications provided
- 2.9ns t_{PD} max. ($V_{CC} = 3.3V$), 10 μ A I_{CC} max.
- Power down high impedance inputs and outputs
- +24mA output drive ($V_{CC} = 3.0V$)
- Implements proprietary noise/EMI reduction circuitry
- Latch-up performance exceeds JEDEC 78 conditions
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V
- Leadless DQFN package

General Description

The LCX07 contains six buffers. The inputs tolerate voltages up to 7V allowing the interface of 5V systems to 3V systems.

The outputs of the LCX07 are open drain and can be connected to other open drain outputs to implement active HIGH wire AND or active LOW wire OR functions.

The 74LCX07 is fabricated with advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.


Ordering Information

| Order Number | Package Number | Package Description |
|---------------------------|----------------|---|
| 74LCX07M | M14A | 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| 74LCX07SJ | M14D | 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LCX07BQX ⁽¹⁾ | MLP14A | 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm |
| 74LCX07MTC | MTC14 | 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Note:

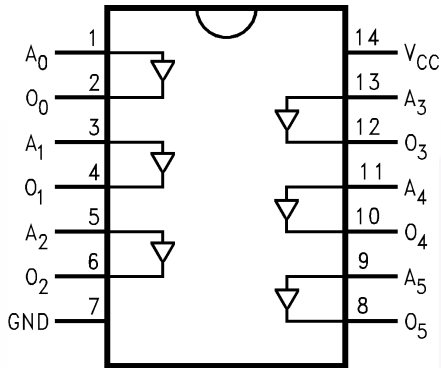
1. DQFN package available in Tape and Reel only.

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

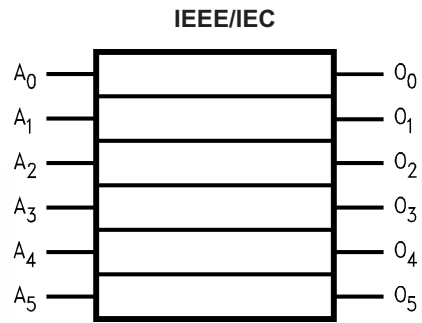
 All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram

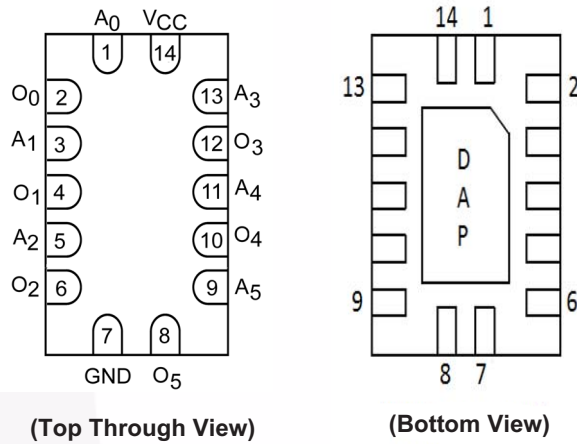
Pin Assignments for SOIC, SOP, and TSSOP



Logic Symbol



Pad Assignments for DQFN



Pin Description

| Pin Names | Description |
|-----------|-------------|
| A_n | Inputs |
| O_n | Outputs |
| DAP | No Connect |

Note: DAP (Die Attach Pad)

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|-----------|---|-----------------|
| V_{CC} | Supply Voltage | -0.5V to +7.0V |
| V_I | DC Input Voltage | -0.5V to +7.0V |
| V_O | DC Output Voltage, Output in HIGH or LOW State ⁽²⁾ | -0.5V to +7.0V |
| I_{IK} | DC Input Diode Current, $V_I < GND$ | -50mA |
| I_{OK} | DC Output Diode Current $V_O < GND$ | -50mA |
| | $V_O > V_{CC}$ | +50mA |
| I_O | DC Output Current | ± 50 mA |
| I_{CC} | DC Supply Current per Supply Pin | ± 100 mA |
| I_{GND} | DC Ground Current per Ground Pin | ± 100 mA |
| T_{STG} | Storage Temperature | -65°C to +150°C |

Note:

2. I_O Absolute Maximum Rating must be observed.

Recommended Operating Conditions⁽³⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Min. | Max. | Units |
|-----------------------|---|------|------|-------|
| V_{CC} | Supply Voltage Operating | 2.0 | 5.5 | V |
| | Data Retention | 1.5 | 5.5 | |
| V_I | Input Voltage | 0 | 5.5 | V |
| V_O | Output Voltage | 0 | 5.5 | V |
| I_{OL} | Output Current $V_{CC} = 4.5V-5.5V$ | | +32 | mA |
| | $V_{CC} = 3.0V-3.6V$ | | +24 | |
| | $V_{CC} = 2.7V-3.0V$ | | +12 | |
| | $V_{CC} = 2.3V-2.7V$ | | +8 | |
| T_A | Free-Air Operating Temperature | -40 | 85 | °C |
| $\Delta t / \Delta V$ | Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$ | 0 | 10 | ns/V |

Note:

3. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = -40°C to +85°C | | Units |
|------------------|---------------------------------------|---------------------|--|---------------------------------|-----------------------|-------|
| | | | | Min. | Max. | |
| V _{IH} | HIGH Level Input Voltage | 2.3–2.7 | | 1.7 | | V |
| | | 2.7–3.6 | | 2.0 | | |
| | | 4.5–5.5 | | 0.7 × V _{CC} | | |
| V _{IL} | LOW Level Input Voltage | 2.3–2.7 | | | 0.7 | V |
| | | 2.7–3.6 | | | 0.8 | |
| | | 4.5–5.5 | | | 0.3 × V _{CC} | |
| V _{OL} | LOW Level Output Voltage | 2.3–5.5 | I _{OL} = 100μA | | 0.2 | V |
| | | 2.3 | I _{OL} = 8mA | | 0.6 | |
| | | 2.7 | I _{OL} = 12mA | | 0.4 | |
| | | 3.0 | I _{OL} = 16mA | | 0.4 | |
| | | 3.0 | I _{OL} = 24mA | | 0.55 | |
| | | 4.5 | I _{OL} = 32mA | | 0.55 | |
| I _I | Input Leakage Current | 2.3–5.5 | 0 ≤ V _I ≤ 5.5V | | ±5.0 | μA |
| I _{OFF} | Power-Off Leakage Current | 0 | V _I or V _O = 5.5V | | 10 | μA |
| I _{CC} | Quiescent Supply Current | 2.3–5.5 | V _I = V _{CC} or GND | | 10 | μA |
| | | 2.3–5.5 | 3.6V ≤ V _I ≤ 5.5V | | ±10 | |
| ΔI _{CC} | Increase in I _{CC} per Input | 2.3–3.6 | V _{IH} = V _{CC} - 0.6V | | 500 | μA |
| | | 4.5–5.5 | | | 1 | |
| I _{OHZ} | Off State Current | 2–5.5 | V _O = 5.5V | | 10 | μA |

AC Electrical Characteristics

| Symbol | Parameter | T _A = -40°C to +85°C, R _L = 500Ω | | | | | | | | Units |
|-------------------------------------|------------------------|---|------|---|------|--|-----|---|-----|-------|
| | | V _{CC} = 5.0V ± 0.5V, C _L = 50pF | | V _{CC} = 3.3V ± 0.3V, C _L = 50pF | | V _{CC} = 2.7V, C _L = 50pF | | V _{CC} = 2.5V ± 0.2V, C _L = 30pF | | |
| | | Min. | Max. | Min. | Max. | Min | Max | Min | Max | |
| t _{PZL} , t _{PLZ} | Propagation Delay Time | 0.5 | 3.0 | 0.8 | 3.7 | 1.0 | 4.4 | 0.8 | 3.8 | ns |

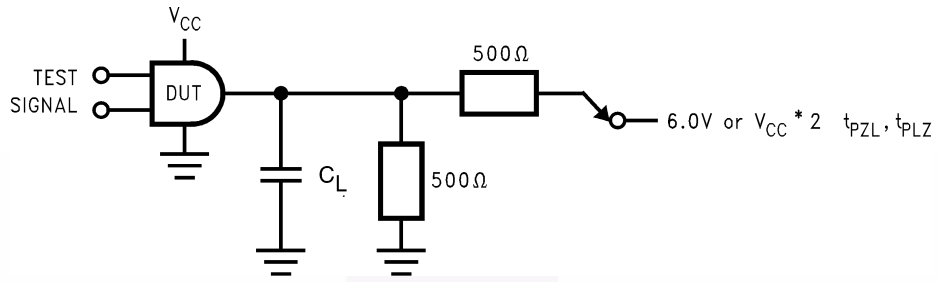
Dynamic Switching Characteristics

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = 25°C | |
|------------------|---|---------------------|---|-----------------------|------|
| | | | | Typical | Unit |
| V _{OLP} | Quiet Output Dynamic Peak V _{OL} | 3.3 | C _L = 50pF, V _{IH} = 3.3V, V _{IL} = 0V | 0.9 | V |
| | | 2.5 | C _L = 30pF, V _{IH} = 2.5V, V _{IL} = 0V | 0.7 | |
| V _{OLV} | Quiet Output Dynamic Valley V _{OL} | 3.3 | C _L = 50pF, V _{IH} = 3.3V, V _{IL} = 0V | -0.8 | V |
| | | 2.5 | C _L = 30pF, V _{IH} = 2.5V, V _{IL} = 0V | -0.6 | |

Capacitance

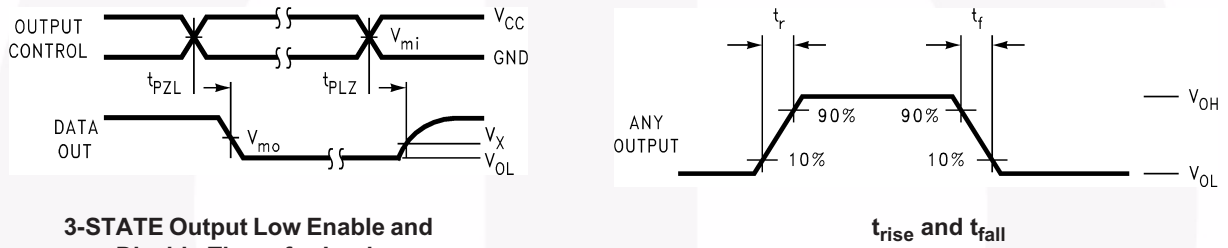
| Symbol | Parameter | Conditions | Typical | Units |
|------------------|-------------------------------|--|---------|-------|
| C _{IN} | Input Capacitance | V _{CC} = Open, V _I = 0V or V _{CC} | 7 | pF |
| C _{OUT} | Output Capacitance | V _{CC} = 3.3V, V _I = 0V or V _{CC} | 8 | pF |
| C _{PD} | Power Dissipation Capacitance | V _{CC} = 3.3V, V _I = 0V or V _{CC} , f = 10MHz | 25 | pF |

AC Loading and Waveforms



| Test | Switch |
|--------------------|--|
| t_{PZL}, t_{PLZ} | $V_{CC} \times 2$ at $V_{CC} = 5.0 \pm 0.5V$ |
| | 6V at $V_{CC} = 3.3 \pm 0.3V$ |
| | $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$ |

Figure 1. AC Test Circuit (C_L includes probe and jig capacitance)



3-STATE Output Low Enable and Disable Times for Logic

| Symbol | V_{CC} | | | |
|----------|-----------------|-----------------|-----------------|------------------|
| | $5.0V \pm 0.5V$ | $3.3V \pm 0.3V$ | 2.7V | $2.5V \pm 0.2V$ |
| V_{mi} | $V_{CC} / 2$ | 1.5V | 1.5V | $V_{CC} / 2$ |
| V_{mo} | $V_{CC} / 2$ | 1.5V | 1.5V | $V_{CC} / 2$ |
| V_x | $V_{OL} + 0.3V$ | $V_{OL} + 0.3V$ | $V_{OL} + 0.3V$ | $V_{OL} + 0.15V$ |
| V_y | $V_{OH} - 0.3V$ | $V_{OH} - 0.3V$ | $V_{OH} - 0.3V$ | $V_{OH} - 0.15V$ |

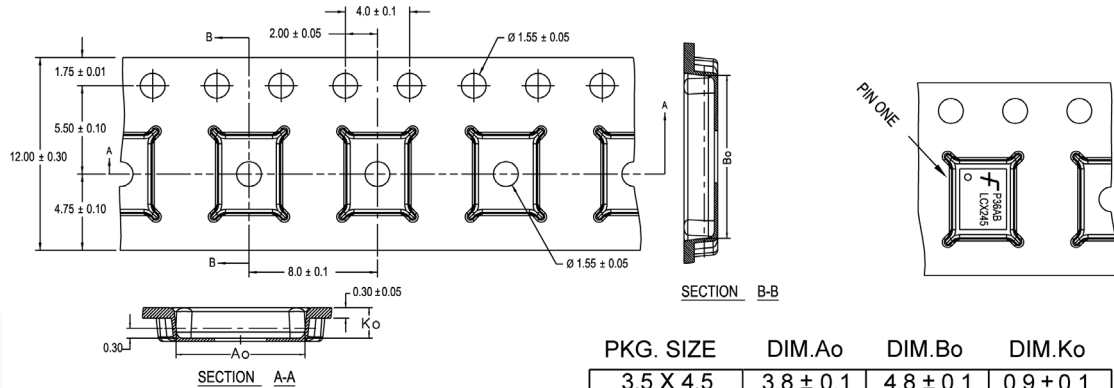
Figure 2. Waveforms (Input Pulse Characteristics; $f = 1MHz, t_r = t_f = 3ns$)

Tape and Reel Specification

Tape Format for DQFN

| Package Designator | Tape Section | Number of Cavities | Cavity Status | Cover Tape Status |
|--------------------|--------------------|--------------------|---------------|-------------------|
| BQX | Leader (Start End) | 125 (Typ.) | Empty | Sealed |
| | Carrier | 3000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (Typ.) | Empty | Sealed |

Tape Dimensions inches (millimeters)



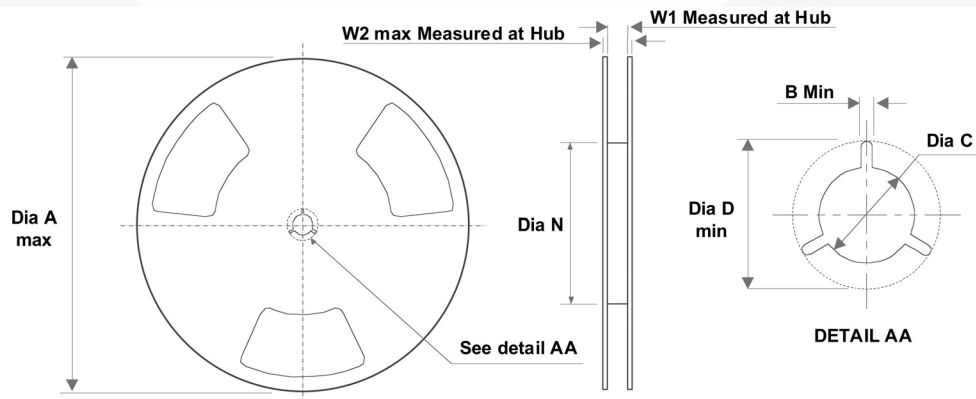
| PKG. SIZE | DIM.Ao | DIM.Bo | DIM.Ko |
|-----------|-----------|-----------|-----------|
| 3.5 X 4.5 | 3.8 ± 0.1 | 4.8 ± 0.1 | 0.9 ± 0.1 |
| 3.0 X 3.0 | 3.3 ± 0.1 | 3.3 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 4.5 | 2.8 ± 0.1 | 4.8 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 3.5 | 2.8 ± 0.1 | 3.8 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 3.0 | 2.8 ± 0.1 | 3.3 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 2.5 | 2.8 ± 0.1 | 2.8 ± 0.1 | 0.9 ± 0.1 |

DIMENSIONS ARE IN MILLIMETERS

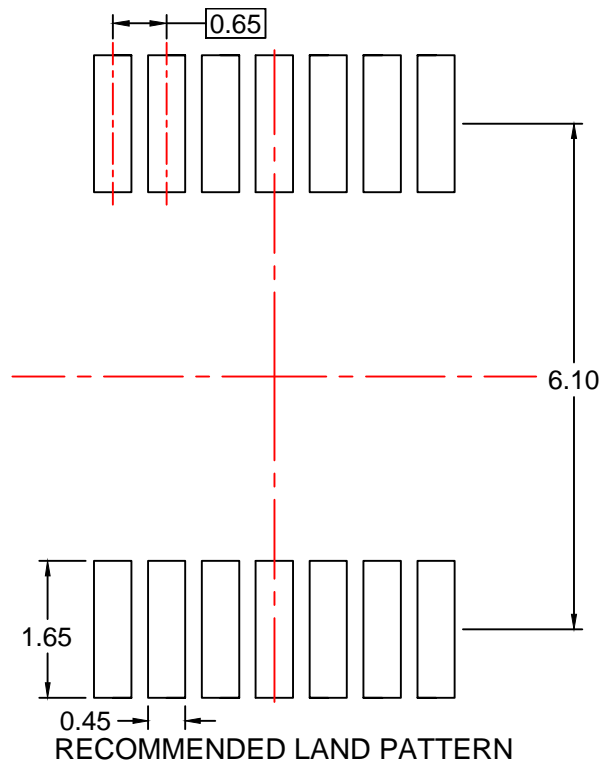
NOTES: unless otherwise specified

1. Cumulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
2. Smallest allowable bending radius.
3. Thru hole inside cavity is centered within cavity.
4. Tolerance is ±0.002[0.05] for these dimensions on all 12mm tapes.
5. Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
6. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
7. Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
8. Controlling dimension is millimeter. Dimension in inches rounded.

Reel Dimensions inches (millimeters)



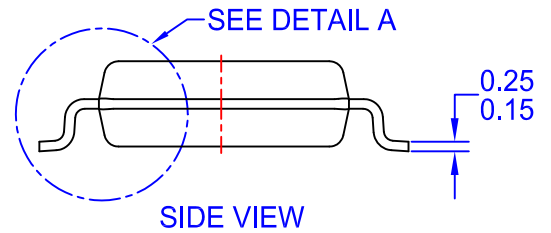
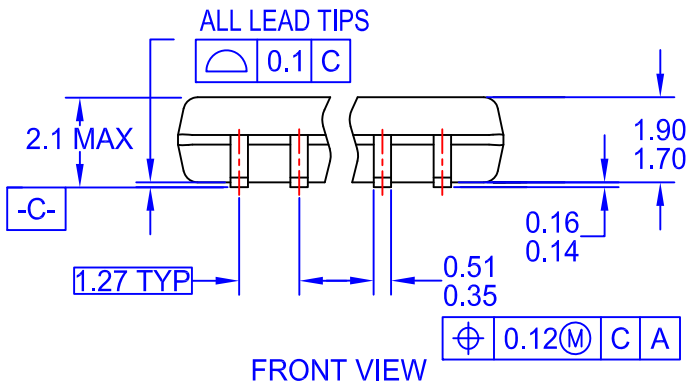
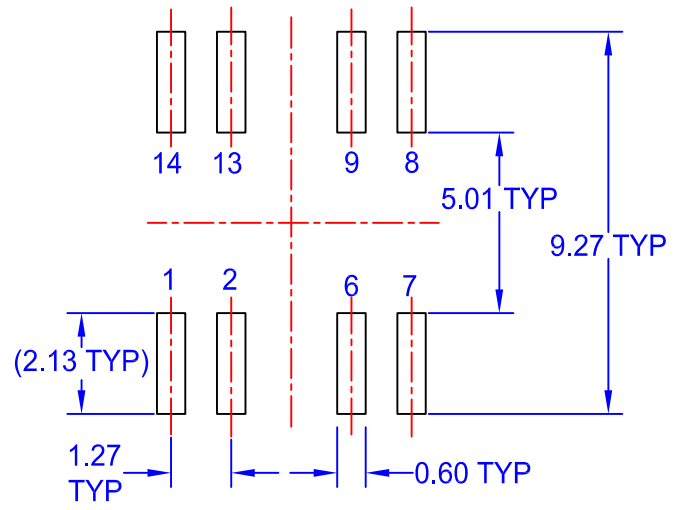
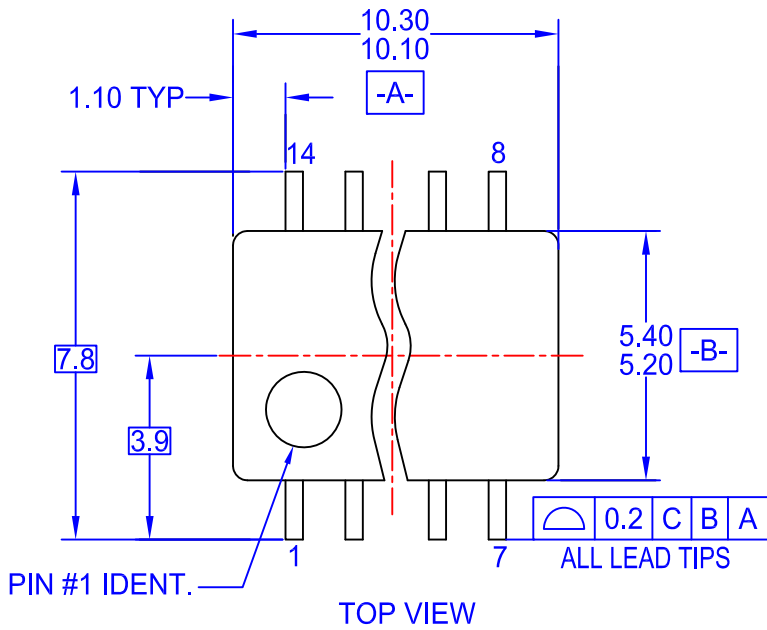
| Tape Size | A | B | C | D | N | W1 | W2 |
|-----------|--------------|--------------|---------------|---------------|---------------|--------------|--------------|
| 12mm | 13.0 (330.0) | 0.059 (1.50) | 0.512 (13.00) | 0.795 (20.20) | 2.165 (55.00) | 0.488 (12.4) | 0.724 (18.4) |



NOTES:

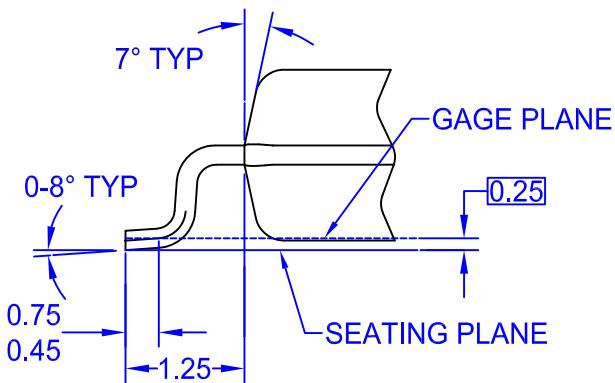
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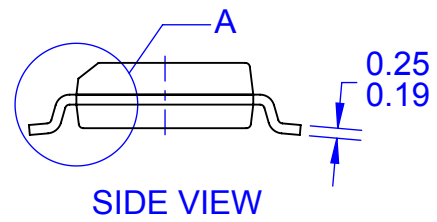
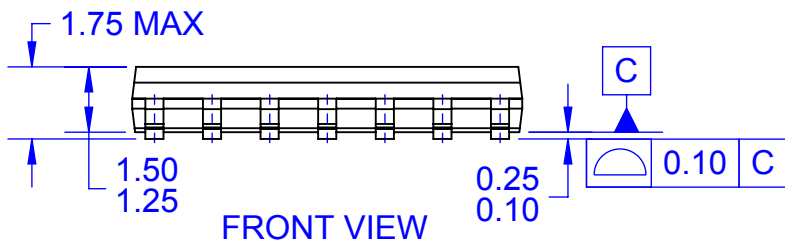
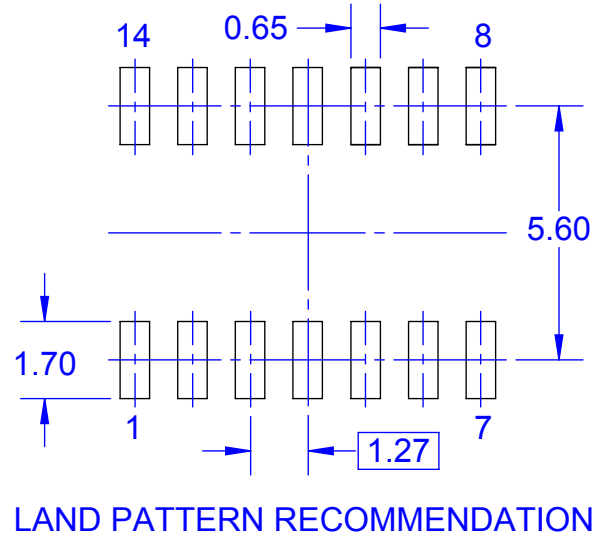




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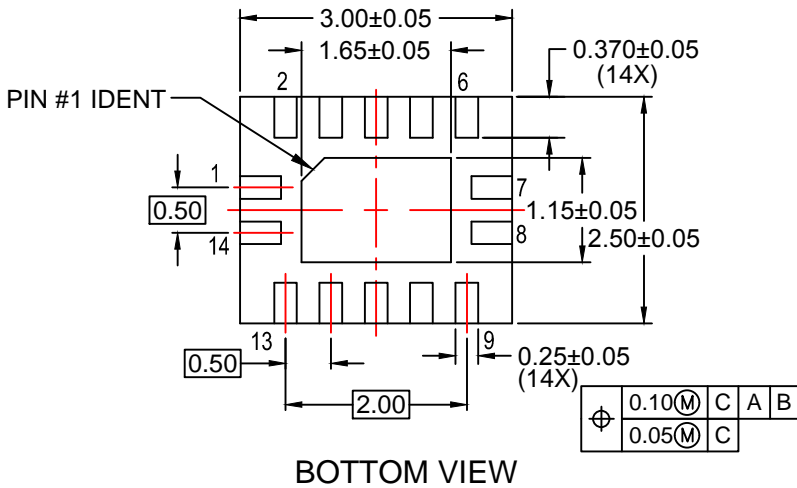
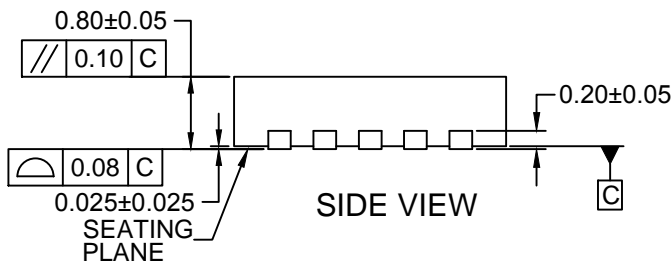
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